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PATENT
Atty. Dkt. No. AMAT/4258/CPI/COPPER/PJS

In re Application of:
Yezdi Dordi

Serial No.: 09/586.736

Confirmation No.: 7891

Filed: June 5, 2000

For: PROGRAMMABLE ANODE
APPARATUS AND
ASSOCIATED METHOD

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Group Art Unit: 1741

Examiner: Leader, W.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited on
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Date Signature

In response to the Restriction Requirement dated October 2, 2001, having a shortened statutory period for response set to expire on November 2, 2001, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below.

Please replace the paragraph at page 2, lines 3-13, with the following paragraph:

Deposition of a metal in electroplating is accomplished by providing an electric current to the seed layer and then exposing the seed layer to an electrolytic solution containing the metal to be deposited. One embodiment of an electroplating system that performs such metal deposition is depicted in FIG. 1. The device, known as a fountain plater 10, deposits metal on the seed layer 15 of a substrate 48. The fountain plater 10 includes an electrolyte cell 12 having a removable substrate support 14, and an anode 16 mounted to the electrolyte cell 12. A positive electrical pole 45 of the controller 42 is